

**REPLY UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: Angyal *et al.*

Conf. No.: 4705

Serial No.: 10/710,706

Art Unit: 2813

Filed: 07/29/2004

Docket No.: FIS920040028US1 (IBMF-0053)

Examiner: Monica D. Harrison

Title: INTERLEVEL DIELECTRIC
LAYER AND METAL LAYER
SEALING

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AFTER FINAL REQUEST FOR RECONSIDERATION

Sir:

INTRODUCTORY COMMENTS

In response to the Final Office Action of February 22, 2006, please re-consider the
rejections based on the following remarks.

*Entered
MDH
1/5/07*